

PRE-PRODUCT CHANGE NOTICE

产品变更申请

PCN#编号:	PCN#20231221-001	Date 日期:	2023/12/21
Subject 主题: SOIC8-WB & SOIC16-WB 框架新增第二供应商永志（江苏泰兴）的 Pre-PCN。 SOIC6-WB & SOIC16-WB add 2nd lead frame supplier Yongzhi (Jiangsu Taixing)。			
Originator 发起人:	Taotao Gu	Phone 电话:	15900401477
Dept. 部门:	Operation		
Change Details 变更说明			
Change Classification 变更等级:	<input checked="" type="checkbox"/> 一级变更 <input type="checkbox"/> 二级变更 <input type="checkbox"/> 三级变更 <input type="checkbox"/> 四级变更		
Change Type 变更类型:	<input type="checkbox"/> Wafer Fabrication 晶圆制造 <input checked="" type="checkbox"/> Assembly 封装 <input type="checkbox"/> Test 测试 <input type="checkbox"/> Product Revision 产品改版 <input type="checkbox"/> Datasheet 产品规格书 <input type="checkbox"/> End of Line 停产 <input type="checkbox"/> Other 其它		
Description of Changes 变更描述: SOIC8-WB&SOIC16-WB 原框架供应商:DCI(马来西亚),增加新的框架供应商:永志(江苏泰兴)。 The SOIC8-WB&SOIC16-WB original lead frame supplier: DCI(Malaysia), add new lead frame supplier Yongzhi (Jiangsu Taixing).			
Reason for Changes 变更原因: 保障供应链的安全性及交付及时性 Ensure supply chain security and delivery timeliness			
Impact of the change (positive or negative) on fit, form, function & reliability 变更（正面或负面）对外观、尺寸、功能和可靠性的影响: 新增第二框架供应商永志（江苏泰兴）的框架设计尺寸，材质均与 DCI 提供的框架相同，基岛背面加钉孔。 The 2nd supplier lead frame Yongzhi (Jiangsu Taixing) with the same design dimensions and materials as the lead frame provided by DCI, add dimple on the back of the die pad.			
SOIC8-WB:		SOIC16-WB:	
DCI	永志	DCI	永志
正面 	正面 	正面 	正面 
背面 	背面 	背面 	背面 
2. 新增第二框架供应商永志（江苏泰兴）对产品外观、产品最终尺寸、产品功能及可靠性无影响。 The appearance, POD, product functionality, and reliability of the 2nd supplier lead frame will not be affected.			
Affected Part Number 受影响产品型号: SOIC8-WB&SOIC16-WB 具体受影响料号如下; Specific affected part numbers can be found below.			
1) SOIC16-WB:			
<ul style="list-style-type: none"> · CA-IS1305AM25W、CA-IS1306AM25W · CA-IS3020W · CA-IS3080WX、CA-IS3082WNX、CA-IS3082WX、CA-IS3086WX · CA-IS3541HWPD · CA-IS3720LW、CA-IS3721HW、CA-IS3721LW、CA-IS3722HW、CA-IS3722LW、CA-IS3730LW · CA-IS3731HW、CA-IS3731LW、CA-IS3740HW、CA-IS3740LW、CA-IS3741HW、CA-IS3741LW · CA-IS3742HW、CA-IS3742LW 			
2) SOIC8-WB:			
<ul style="list-style-type: none"> · CA-IS1300G25G · CA-IS3020G、CA-IS3021G、CA-IS3050G、CA-IS3052G 			

- CA-IS3522HGP、CA-IS3720HG、CA-IS3720LG、CA-IS3721HG、CA-IS3721LG、CA-IS3722HG、CA-IS3722LG

Verification Plan 验证计划:

Item	23WW52	24WW01	WW02	WW03	WW04	WW05	WW06	WW07
Qual lot build								
封装可靠性 Package reliability plan								

Implementation Date 实施日期:

预计新增第二供应商框架的实施日期为 2024 年 3 月初。

It's planned to completed the qualification by the end of Mar. 2024.

Appendix 附件:
Chipanalog Approval/Comment:

Approval Not approval Other

Date: 2023 年 12 月 21 日

Name/ title: Chen, Liang/Quality Director

Customer Approval/Comment:

Approval Not approval Other

Date:

Name/ title:

Remark: After Chipanalog notice of change is issued, for class 1 change, please review within 30 calendar days. For class 2 change, please review within 15 calendar days. If there is any problem, please feedback timely. If there is no feedback, you will agree to the change by default.

备注: 川土变更通知发出后, 一级变更请您在 30 天内进行评审, 二级变更请您在 15 天内进行评审。若有问题, 请您及时反馈。若未反馈, 默认您同意变更。

For additional information regarding this change, contact your local sales representative or contact the PCN administrator at chenliang@chipanalog.com.

有关此更改的其他信息, 请联系销售代表或 PCN 管理员: chenliang@chipanalog.com.